

MA27P02

Silicon epitaxial planar type

For high frequency switch

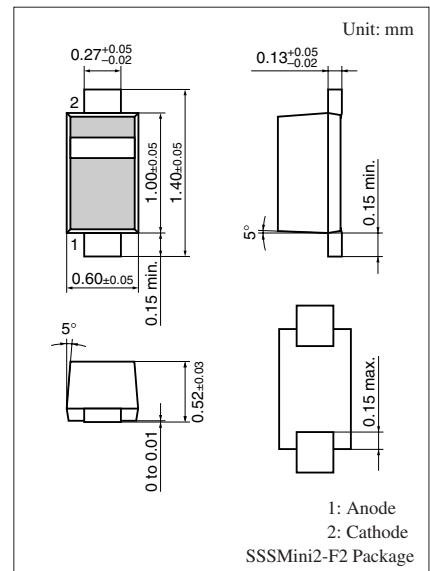
■ Features

- Small terminal capacitance C_t
- Small forward dynamic resistance r_f
- Ultraminiature package and surface mounting type
1.0 mm × 0.6 mm (height: 0.52 mm)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	60	V
Forward current	I_F	100	mA
Power dissipation *	P_D	150	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *: With a glass epoxy PC board



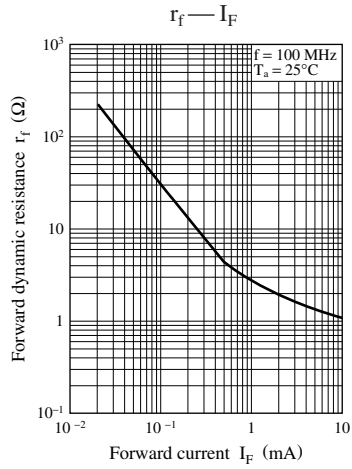
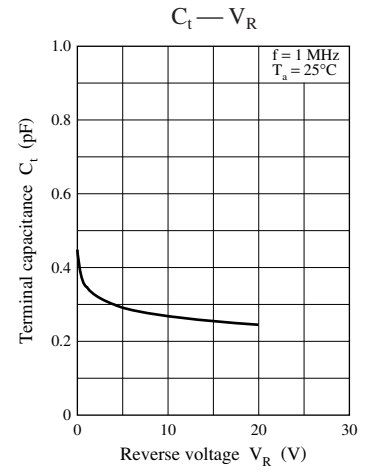
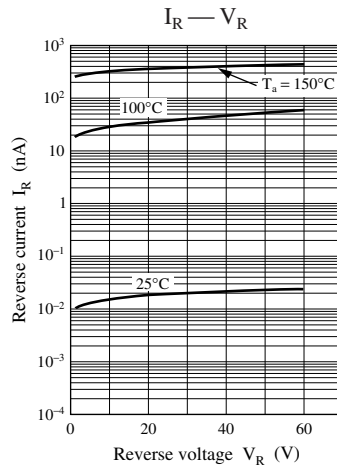
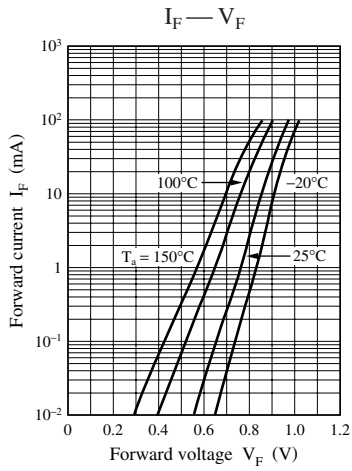
Marking Symbol: Y

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 10 \text{ mA}$			1.0	V
Reverse current	I_R	$V_R = 60 \text{ V}$			100	nA
Terminal capacitance	C_t	$V_R = 1 \text{ V}, f = 1 \text{ MHz}$			0.5	pF
Forward dynamic resistance *	r_f	$I_F = 10 \text{ mA}, f = 100 \text{ MHz}$			2.0	Ω

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. *: r_f measurement device ; agilent model 4291B



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